

**SURS8360B** 

# Ultra-fast Rectifiers MURS360B, NRVUS360VB,

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

#### **Features**

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- NRVUS and SURS8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **Mechanical Characteristics**

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-O @ 0.125 in
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Rating:
  - ♦ Human Body Model (HBM) 3B (> 8 kV)
  - ◆ Charged Device Model (CDM) > 1000 V

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	600	>
Average Rectified Forward Current	I <sub>F(AV)</sub>	3.0 @ T <sub>L</sub> = 105°C	Α
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	100	Α
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	- 65 to +175	ç

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## ULTRAFAST RECTIFIERS 3 AMPERES 600 VOLTS



SMB CASE 403A

#### **MARKING DIAGRAM**



B36B = Specific Device Code A = Assembly Location

Y = Year

WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MURS360BT3G	SMB (Pb-Free)	2,500 / Tape & Reel
NRVUS360VBT3G NRVUS360VBT3G-GA01	SMB (Pb-Free)	2,500 / Tape & Reel
NRVUS360VDBT3G	SMB (Pb-Free)	2,500 / Tape & Reel
SURS8360BT3G	SMB (Pb-Free)	2,500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### MURS360B, NRVUS360VB, SURS8360B

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1) Thermal Resistance, Junction-to-Ambient (Note 1)	$egin{aligned} R_{ hetaJL} \ R_{ hetaJA} \end{aligned}$	14 125	°C/W

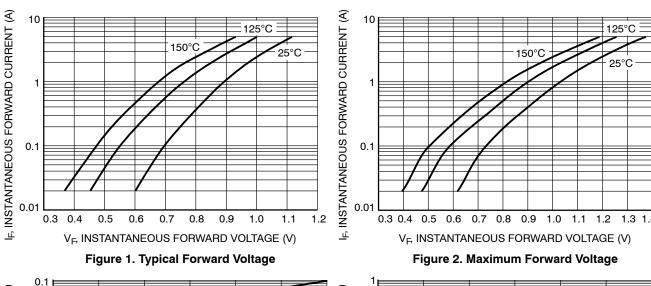
<sup>1.</sup> Mounted with minimum recommended pad size, PC Board FR4.

#### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) ( $i_F = 3.0 \text{ A}, T_J = 25^{\circ}\text{C}$ ) ( $i_F = 3.0 \text{ A}, T_J = 150^{\circ}\text{C}$ )	VF	_ 0.83	1.25 1.05	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, T <sub>J</sub> = 25°C) (Rated DC Voltage, T <sub>J</sub> = 150°C)	İR	- 95	3.0 150	μА
Maximum Reverse Recovery Time ( $i_F = 1.0$ A, di/dt = 50 A/ $\mu$ s) ( $i_F = 0.5$ A, $i_R = 1.0$ A, $I_R$ to 0.25 A)	t <sub>rr</sub>	- -	75 50	ns
Maximum Forward Recovery Time (i <sub>F</sub> = 1.0 A, di/dt = 100 A/μs, Rec. to 1.0 V)	t <sub>fr</sub>	_	50	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### TYPICAL CHARACTERISTICS



I, REVERSE CURRENT (mA) REVERSE CURRENT (mA) 150°C 0.01 0.1 150°C 125°C 0.001 0.01 125°C 0.0001 0.001 25°C 0.00001 0.0001 0.000001 0.00001 100 300 100 600 200 400 500 600 200 300 400 500 V<sub>r</sub>, REVERSE VOLTAGE (V) V<sub>r</sub>, REVERSE VOLTAGE (V)

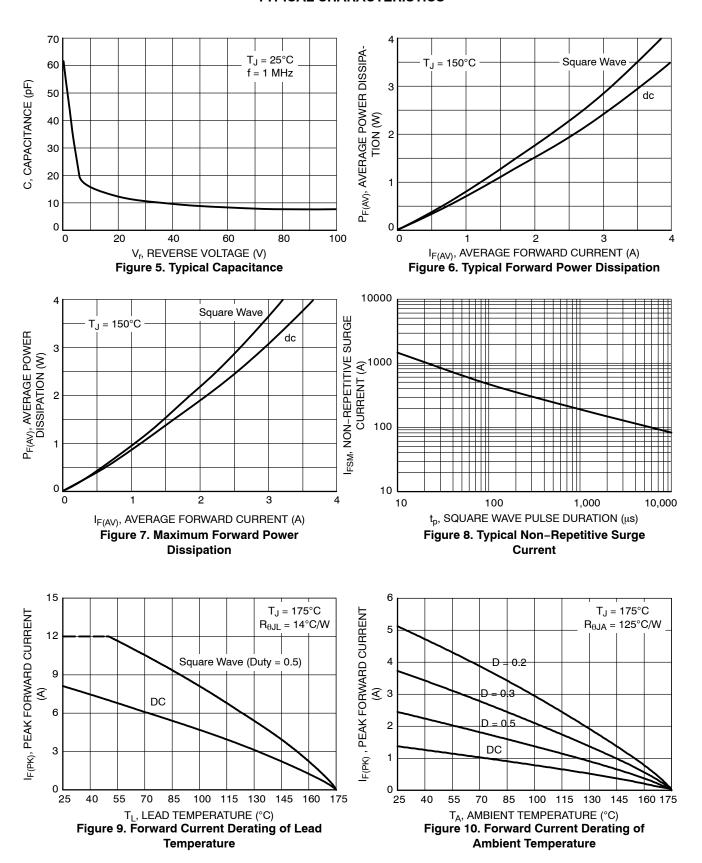
**Figure 3. Typical Reverse Current** 

Figure 4. Maximum Reverse Current

<sup>2.</sup> Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

#### MURS360B, NRVUS360VB, SURS8360B

#### **TYPICAL CHARACTERISTICS**



<sup>\*</sup>Typical performance based on a limited sample size. onsemi does not guarantee ratings not listed in the Maximum Ratings table.

### MURS360B, NRVUS360VB, SURS8360B

#### **TYPICAL CHARACTERISTICS**

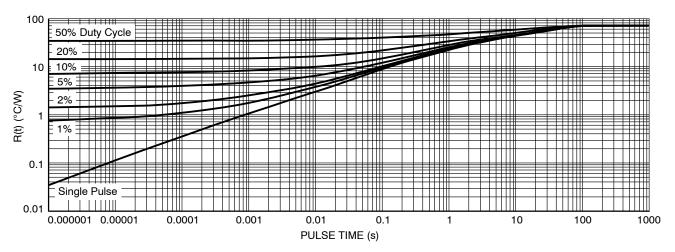


Figure 11. Thermal Response, Junction-to-Ambient



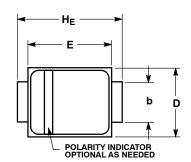


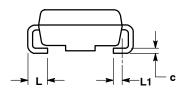
**SMB** CASE 403A-03 **ISSUE J** 

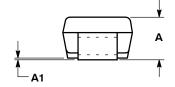
**DATE 19 JUL 2012** 

SCALE 1:1 **Polarity Band** 

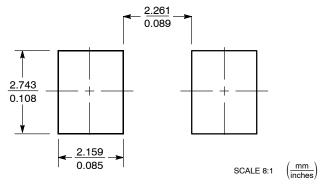
Non-Polarity Band







#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCL.
- 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	MOM	MAX	
Α	1.95	2.30	2.47	0.077	0.091	0.097	
A1	0.05	0.10	0.20	0.002	0.004	0.008	
b	1.96	2.03	2.20	0.077	0.080	0.087	
С	0.15	0.23	0.31	0.006	0.009	0.012	
D	3.30	3.56	3.95	0.130	0.140	0.156	
E	4.06	4.32	4.60	0.160	0.170	0.181	
HE	5.21	5.44	5.60	0.205	0.214	0.220	
L	0.76	1.02	1.60	0.030	0.040	0.063	
L1	0.51 REF				0.020 REF		

#### **GENERIC MARKING DIAGRAM\***





**Polarity Band** 

Non-Polarity Band

XXXXX = Specific Device Code = Assembly Location Α

= Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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